

Laurell Spin-Coaters

- **Spin-coating of photoresist layers**
- Max. rpm: 12000
- Variable time selection
- Model: WS-650MZ-23NNP
WS-400A-6NPP/LITE



Oven for Photoresist baking

- **Soft and hard baking of photoresist layer**
- Temperature: 100 °C and 130 °C
- Sample size up to 6"
- Automated time controlling

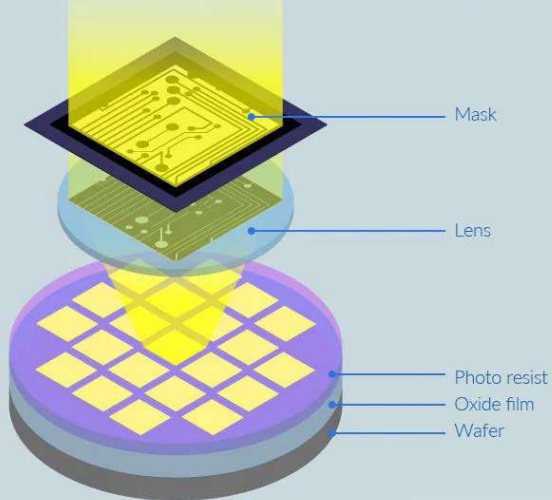


Photo-Process Wet bench

- Developing patterns, removing photoresist
- Solvents
- Hot Plates
 - Maximum Temperature is 400°C
- Developers
 - AZ 917-MIF



Photolithography that draws circuits on the wafer through light



Samsung Semiconstorey
samsungsemiconstorey.com

MJB3 Mask Aligner and exposure system

- To **transfer patterns on photoresist layers**
- Exposure intensity: 29 mW/cm² at 365 nm
- Substrate size: up to 3"
- Mask size 4"
- Minimum feature size: **2.5 μm**
- Contact Mode: hard, soft and vacuum mode

